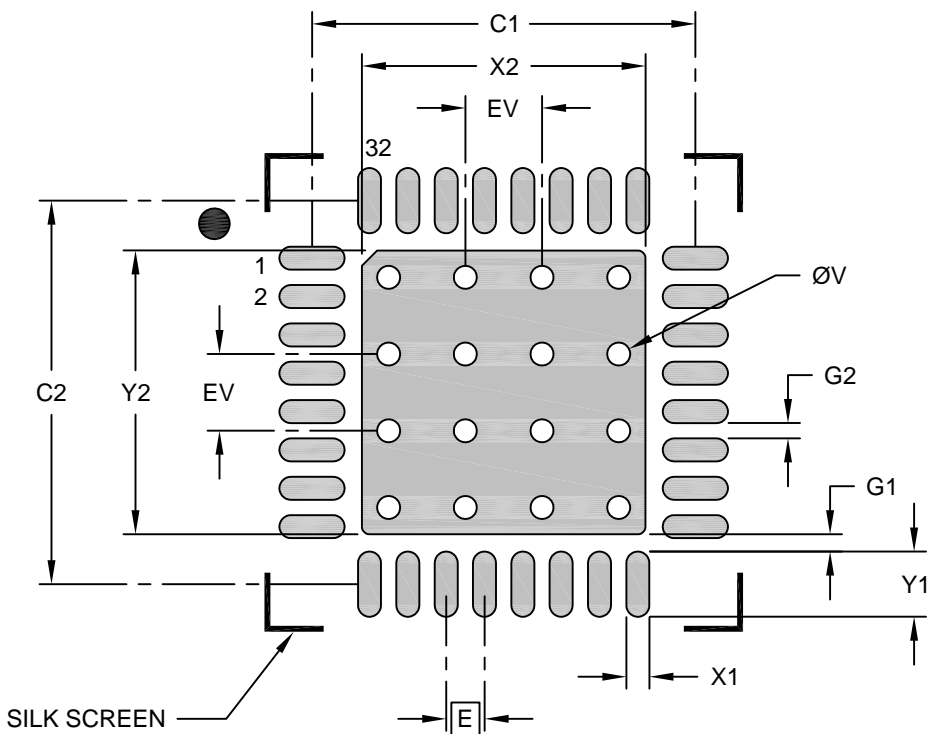


32-Lead Very Thin Plastic Quad Flat, No Lead Package (S8B) - 5x5 mm Body [VQFN] With 3.60 mm Exposed Pad; Atmel Legacy Global Package Code ZKV

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

| Dimension Limits | Units | MILLIMETERS | | |
|----------------------------------|-------|-------------|------|------|
| | | MIN | NOM | MAX |
| Contact Pitch | E | 0.50 BSC | | |
| Optional Center Pad Width | X2 | | | 3.70 |
| Optional Center Pad Length | Y2 | | | 3.70 |
| Contact Pad Spacing | C1 | | 5.00 | |
| Contact Pad Spacing | C2 | | 5.00 | |
| Contact Pad Width (X32) | X1 | | | 0.30 |
| Contact Pad Length (X32) | Y1 | | | 0.85 |
| Contact Pad to Center Pad (X32) | G1 | 0.23 | | |
| Contact Pad to Contact Pad (X28) | G2 | 0.20 | | |
| Thermal Via Diameter | V | | 0.30 | |
| Thermal Via Pitch | EV | | 1.00 | |

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process